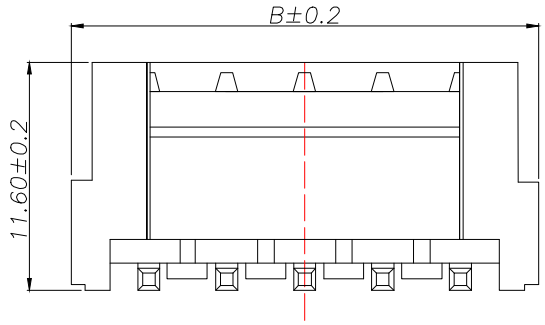
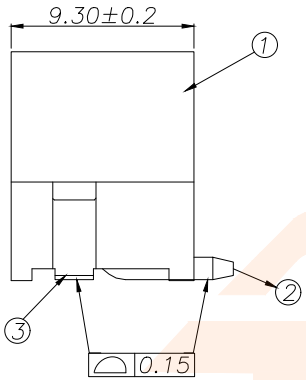
Process Capable

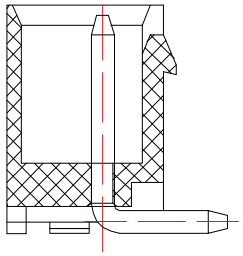
RoHS Compliant 2011/65/EU

Compliant Halogen Free

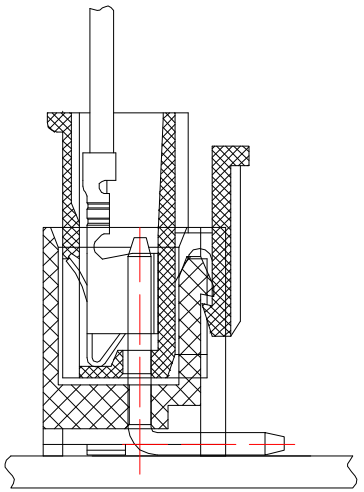
REV.	ECN NO.	DESCRIPTION	DATE	DESIGN



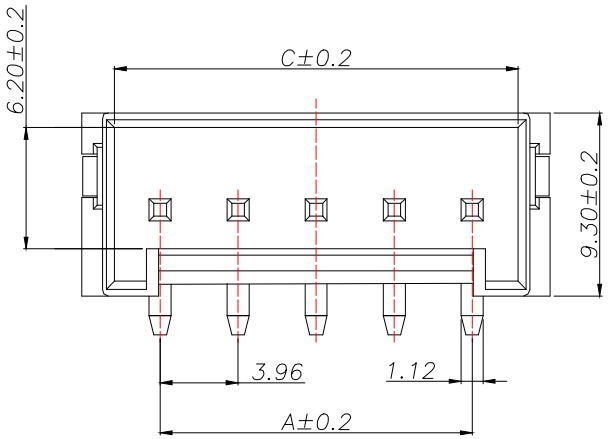




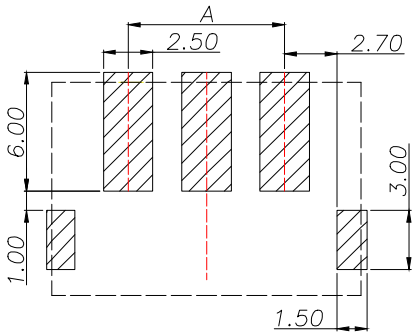
SECTION A–A



SUGGESTED PCB LAYOUT
(COMPONENT SIDE)



Part No	Pin	A	B	C
D396E1L1-2W2P41	2	3.96	11.88	8.60
D396E1L1-2W3P41	3	7.92	15.84	12.56
D396E1L1-2W4P41	4	11.88	19.80	16.52
D396E1L1-2W5P41	5	15.84	23.76	20.48
D396E1L1-2W6P41	6	19.80	27.72	24.44
D396E1L1-2W7P41	7	23.76	31.68	28.40
D396E1L1-2W8P41	8	27.72	35.64	32.36
D396E1L1-2W9P41	9	31.68	39.60	36.32
D396E1L1-2W10P41	10	35.64	43.56	40.28



SUGGESTED PCB LAYOUT
(COMPONENT SIDE)

技术要求:

1.塑件材料:LCP(UL-94V-0)
2.接触件:黄铜镀锡
3.接触电阻:≤30mΩ
4.绝缘电阻:≥1000MΩ
5.额定电压:250V AC DC
6.额定电流:7.0A AC DC
7.耐压:能承受1000V AC/Minute
8.工作温度:-25°~+85°
9.可焊性试验:浸锡面积≥95%温度260,时间2.5±0.5秒
10.铅和镉等六大有害物质含量要符合环保要求.

序号	名称	材料	数量	备注
3	焊片 Fitting Nail	黄铜	2	电镀(锡):整个表面镀底镍30u"MIN,再镀锡80u"MIN
2	端子 Contact	黄铜	N*1	电镀(锡):整个表面镀底镍30u"MIN,再镀锡80u"MIN
1	基座 Wafer	LCP (UL94V-0)	1	米色

TOLERANCE		深圳聚兴泰电子科技有限公司 Shenzhen Juxingtai Electronic Technology Co., Ltd	
X.X ±0.30	X.° ±5°	PART NO. D396E1L1-2WXP41	TITLE: 3.96MM 立贴
.XX ±0.20	X.X° ±1°		
.XXX ±0.10	X.XX°±0.5°	DESIGN: Ethan	MANUFACTURE DWG
UNITS	mm	CHED: Olvia	SCALE N:A / SHEET 1/1
MATERILA	— — —	APPD: Ava	
FINISH	— — —		